IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserve international and Pan-American copyright conventions.		All rights reserved und	der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assemble level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering response.						ssembly with low responsibility.		
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				ials and Mfg Information				
upplier	Information								,					
Company n	name*	Company ur	Company unique ID			Unique ID Authority				Response Date*				
onsemi											2025-07-09			
Contact Na	me	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-E	nv-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Veight*	UOM	Unit Type
	FDMF5071 90A GEN4 Smart P		Power Stage		2025-07-09		MY5		8	6.36325	mg	Each		
Ianufac	turing Proccess Inform	ation												·
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S			Peak Proce	Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles				
I	Matte Tin (Sn) - annealed	(CU Alloy	1			260		C	30	secono	ds 3		
omments														
vel 1 - ma	ximum time at peak tempera	ture during so	ldering is 10-3	30 seconds										
or more ir	nformation regarding materia	al composition	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.80036	mg	Supplier	Zinc (Zn)	7440-66-6		0.0082	mg
			Supplier	Iron (Fe)	7439-89-6		0.1632	mg
			Supplier	Copper (Cu)	7440-50-8		6.6236	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0054	mg
Clip Attach	0.1	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0075	mg
			Supplier	Proprietary	Proprietary Data		0.0065	mg
			Supplier	Bismaleimide	13676-54-5		0.028	mg
			Supplier	PTFE	9002-84-0		0.058	mg
Die	2.76287	mg	Supplier	Silicon (Si)	7440-21-3		2.7629	mg
Die Attach Solder	4.40103	mg	Supplier	Silver (Ag)	7440-22-4		0.11	mg
			A	Lead (Pb)	7439-92-1	7a	4.071	mg
			Supplier	Tin (Sn)	7440-31-5		0.2201	mg
Lead Frame	32.9996	mg	Supplier	Silver (Ag)	7440-22-4		1.65	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0396	mg
			Supplier	Iron (Fe)	7439-89-6		0.792	mg
			Supplier	Copper (Cu)	7440-50-8		30.4916	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0264	mg
Mold Compound-Black	36.0995	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.3465	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1805	mg
			Supplier	Silica (SiO2)	14464-46-1		31.7676	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.805	mg
Plating	2.99983	mg	Supplier	Tin (Sn)	7440-31-5		2.9998	mg
Wire Bond - Cu	0.200061	mg	Supplier	Palladium (Pd)	7440-05-3		0.0036	mg
			Supplier	Gold (Au)	7440-57-5		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.1963	mg